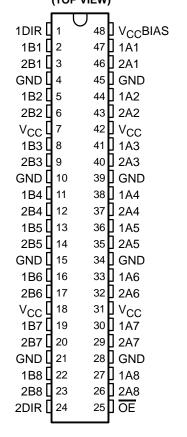
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- **Members of the Texas Instruments** Widebus™ Family
- Support the VME64 ETL Specification
- Reduced, TTL-Compatible, Input Threshold Range
- High-Drive Outputs ($I_{OH} = -60 \text{ mA}$, I_{OL} = 90 mA) Support 25- Ω Incident-Wave Switching
- **V_{CC}BIAS** Pin Minimizes Signal Distortion **During Live Insertion**
- Internal Pullup Resistor on OE Keeps **Outputs in High-Impedance State During Power Up or Power Down**
- Distributed V_{CC} and GND Pins Minimize **High-Speed Switching Noise**
- Equivalent 25- Ω Series Damping Resistor on B Port
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors

description

The 'ABTE16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements. These devices can be used as two 8-bit transceivers or

SN54ABTE16245 . . . WD PACKAGE SN74ABTE16245 . . . DGG OR DL PACKAGE (TOP VIEW)



one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated. When \overline{OE} is low, the device is active.

The B port has an equivalent 25- Ω series output resistor to reduce ringing. Active bus-hold inputs also are on the B port to hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via V_{CC} BIAS, which establishes a voltage between 1.3 V and 1.7 V when V_{CC} is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments



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ORDERING INFORMATION

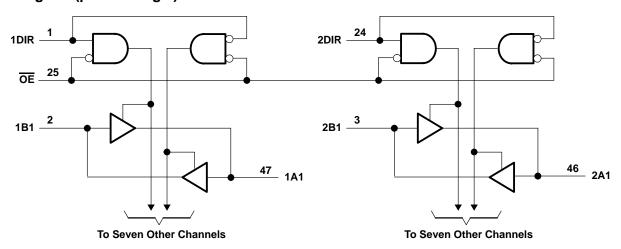
TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP – DL	ABTE16245			
–40°C to 85°C		Tape and reel	SN74ABTE16245DLR	ADTE 10245	
	TSSOP – DGG	Tape and reel	SN74ABTE16245DGGR	ABTE16245	
–55°C to 125°C	CFP – WD	Tube	SNJ54ABTE16245WD	SNJ54ABTE16245WD	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 8-bit section)

INP	UTS	ODED ATION					
OE	DIR	OPERATION					
L	L	A data to B bus					
L	Н	B data to A bus					
Н	X	Isolation					

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC} and V _{CC} BIAS	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, I _O	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The package thermal impedance is calculated in accordance with JESD 51-7.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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recommended operating conditions (see Note 3)

			SN54	ABTE16	6245	SN74	ABTE16	3245	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
V _{CC} , V _{CC} BIAS	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
V	High level input voltage	ŌĒ	2			2			V	
VIH	High-level input voltage	Except OE	1.6			1.6			V	
Min	Low lovel input voltage	ŌĒ			0.8			0.8	V	
VIL	Low-level input voltage	Except OE			1.4			1.4	V	
٧ _I	Input voltage		0		VCC	0		Vcc	V	
lou	High lovel output ourrent	B bus			-12			-12	mA	
ЮН	High-level output current	A bus			-24			-60	mA	
la.	Low lovel output oursest	B bus			12			12	A	
lOL	Low-level output current	A bus			64		90		mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10			10	ns/V	
T _A	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAF	DAMETED	TEST 00	NDITIONS	SN	54ABTE1	6245	SN	74ABTE	16245	LIAUT	
PAR	RAMETER	1551 CC	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V	
		V _{CC} = 5.5 V,	I _{OH} = -100 μA			V _{CC} -0.2			V _{CC} -0.2		
	B port	V 45V	I _{OH} = -1 mA	2.4			2.4				
V		V _{CC} = 4.5 V	I _{OH} = -12 mA	2			2			V	
VOH		$V_{CC} = 5.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$			4.5			4.5	V	
	A port	V 45V	I _{OH} = -32 mA	2.4			2.4				
		V _{CC} = 4.5 V	I _{OH} = -64 mA				2				
	D nort	V 45V	I _{OL} = 1 mA			0.4			0.4		
V	B port	V _{CC} = 4.5 V	I _{OL} = 12 mA						0.8	V	
VOL	A port	V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55			0.55	V	
	A port	vCC = 4.5 v	I _{OL} = 90 mA						0.9		
	(hold) B port	V 45V	V _I = 0.8 V	100			100				
I _I (hold)		V _{CC} = 4.5 V	V _I = 2 V	-100			-100			μΑ	
		$V_{CC} = 5.5 \text{ V},$	V _I = 0 to 5.5 V			±500			±500		
1.	Control inputs	V _{CC} = 5.5 V,	5.5 V, V _I = V _{CC} or GND			±1			±1		
tı	A or B ports	vCC = 5.5 v,	AL = ACC OLGIAD			±20			±20	μΑ	
lozh [‡]	A port	$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			10			10	μΑ	
lozL [‡]	A port	V _{CC} = 5.5 V,	V _O = 0.5 V			-10			-10	μΑ	
1-	A port	V 55V	V- 25V	-50	-120	-180	-50		-180	mA	
Ю	B port	V _{CC} = 5.5 V,	V _O = 2.5 V	-25	-52	-90	-25		-90	mA	
l _{off}		$V_{CC} = 0$, V_{I} or $V_{O} \le$	4.5 V, V _{CC} BIAS = 0			±100			±100	μΑ	
			Outputs high		28	36		28	36		
Icc	ICC A or B ports	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		38	48		38	48	mA	
		V1 = VCC 01 014B	Outputs disabled		20	32		20	32		
loop	A or D ports	V _{CC} = 5 V,	OE high		0.02			0.02		mA/	
ICCD	A or B ports	C _L = 50 pF	OE low		0.33			0.33		MHz	
C _i	Control inputs	V _I = 2.5 V or 0.5 V				10		2.5	4	pF	
C _{io}	I/O ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$				13		4.5	8	pF	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

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live-insertion specifications over recommended operating free-air temperature range

DADA	METER		SN54	ABTE16	6245	SN74ABTE16245			UNIT		
PARAI	VIETER	TEST CONDITIONS				TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
loo (Va	a PIAC)	$V_{CC} = 0 \text{ to } 4.5$ $I_{O(DC)} = 0$	CC = 0 to 4.5 V, V _{CC} BIAS = 4.5 V to 5.5 V, D(DC) = 0				700		250	700	
ICC (VC	:Свіко)	$V_{CC} = 4.5 \text{ V to}$ $I_{O(DC)} = 0$	V to 5.5 V ‡ , V _{CC} BIAS = 4.5 V to 5.5 V,				20			20	μΑ
Va	A nort	V22 - 0	V _{CC} BIAS = 4.5 V to 5.5 V	/	1.1	1.5	1.9	1.1	1.5	1.9	V
Vo	A port $VCC = 0$		V _{CC} BIAS = 4.75 V to 5.2	1.3	1.5	1.7	1.3	1.5	1.7	V	
la	I_O A port $V_{CC} = 0$,		VCCBIAS = 4.5 V	V _O = 0	-20		-100	-20		-100	μΑ
l '0			V (ССыдо = 4.5 V	V _O = 3 V	20		100	20		100	μΑ

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ ₀ ۲٫	V _{CC} = 5 V, T _A = 25°C			SN54ABTE16245		SN74ABTE16245		
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
^t PLH	А	В	1.5	3.3	4.2	1.5	5.4	1.5	5.2	ns	
^t PHL	A	Ь	1.5	3.8	4.6	1.5	5.4	1.5	5.2	115	
^t PLH	В	۸	1.5	3	3.8	1.5	4.7	1.5	4.5	no	
^t PHL	В	Α	1.5	3.1	4	1.5	4.7	1.5	4.5	ns	
^t PZH	ŌĒ	^	2	3.9	5.3	2	6.4	2	6.2		
tpZL	OE .	Α	2	4.4	5.9	2	7	2	6.8	ns	
^t PZH		В	2	4.5	6	2	7.3	2	7.1		
tPZL	ŌĒ	В	2	5	6.4	2	7.5	2	7.3	ns	
^t PHZ	ŌĒ	Δ.	2	4.9	5.9	2	7	2	6.7		
^t PLZ] OE	А	2	3.7	4.6	2	5.4	2	5.1	ns	
^t PHZ	ŌĒ	В	2	5.2	6.2	2	7.2	2	7		
^t PLZ]		2	4	5	2	5.8	2	5.5	ns	



[‡] VCC - 0.5 V < VCCBIAS

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extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 2)

PARAMETER	RAMETER FROM TO (OUTPUT)		LOAD	V _{CC} = 5 V, T _A = 25°C			SN54ABTE16245		SN74ABTE16245		UNIT
	(IIVI O1)	(0011 01)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	В	А	Rχ = 13 Ω	1.5	3.2	4	1.5	5	1.5	4.8	ns
t _{PHL}	ם	^	Λχ = 13 22	1.5	3.8	4.7	1.5	5.8	1.5	5.6	115
tPLH	В	А	Rχ = 26 Ω	1.5	3.1	4	1.5	4.8	1.5	4.6	ns
tPHL	ם	^	Λχ = 20 12	1.5	3.5	4.4	1.5	5.2	1.5	4.9	115
t _{PLH}	В	А	By - 56 O	1.5	3	3.8	1.5	4.7	1.5	4.5	ns
t _{PHL}	Б	A	$R\chi = 56 \Omega$	1.5	3.3	4.2	1.5	5.1	1.5	4.7	115
	В	А	R _X = Open		0.1	0.6		2		2	
^t sk(p)	А	В	R _X = Open		0.4	0.8		2		2	ns
	В	А	$R_X = 26 \Omega$		0.3	8.0		2		2	
	В	А	R _X = Open		0.3	0.7		1.3		1.3	
tsk(o)	Α	В	R _X = Open		0.7	1.1		1.3		1.3	ns
	В	А	$R_X = 26 \Omega$		0.5	1		1.3		1.3	
tt†	В	А	$R_X = 26 \Omega$	0.5	0.8	1.5	0.5	1.5	0.5	1.5	ns
t _t ‡	Α	В	R _X = Open	3.5	5.5	7.3	3.5	8.1	3.5	7.9	ns

 $[\]dagger$ t_t is measured between 1 V and 2 V of the output waveform.

extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (see Figures 1 and 2)

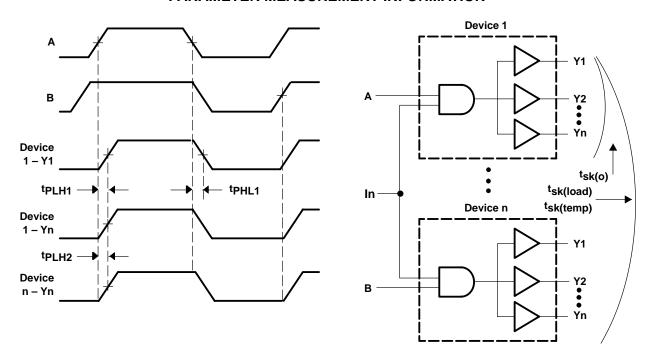
PARAMETER	FROM	то	TEST CONDITIONS	LOAD	SN54ABTE16245		SN74ABTE16245		UNIT
PARAMETER	(INPUT)	NPUT) (OUTPUT) TEST SONDITIONS ESAB	LOAD	MIN	MAX	MIN	MAX	UNIT	
• • • •	Α	В	V _{CC} = constant,			3		2.5	
^t sk(temp)	В	Α	$\Delta T_A = 20^{\circ}C$	$R\chi = 56 \Omega$		4.5		4	ns
^t sk(load)	В	В	V _{CC} = constant, Temperature = constant	$R_X = 13, 26,$ or 56Ω		4.5		4	ns



[‡]t_t is measured between 10% and 90% of the output waveform.

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PARAMETER MEASUREMENT INFORMATION

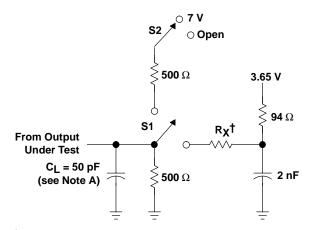


- NOTES: A. Pulse skew, $t_{sk(p)}$, is defined as the difference in propagation-delay times t_{PLH1} and t_{PHL1} on the same terminal at identical operating conditions.
 - B. Output skew, t_{Sk(0)}, is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g., |t_{PLH1} t_{PLH2}|).
 - C. Temperature skew, $t_{sk(temp)}$, is the output skew of two devices, both having the same value of $V_{CC} \pm 1\%$ and with package temperature differences of 20°C.
 - D. Load skew, $t_{sk(load)}$, is measured with R_X in Figure 2 at 13 Ω for one unit and 56 Ω for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics

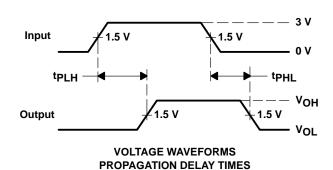
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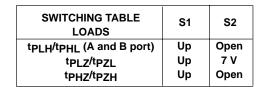
PARAMETER MEASUREMENT INFORMATION



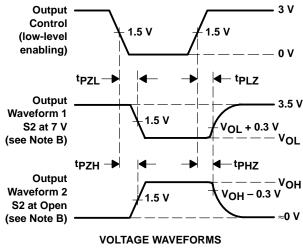
 $\dagger R_{X} = 13, 26, \text{ or } 56 \Omega$

LOAD CIRCUIT FOR OUTPUTS





EXTENDED SWITCHING TABLE	S1	S2
LOADS	31	32
tpLH/tpHL/tsk (A port)	Down	Х
tpLH/tpHL/tsk (B port)	Up	Open
t _t (A port) (see Note E)	Down	Х
t _t (B port) (see Note F)	Up	Open



ENABLE AND DISABLE TIMES

- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_t is measured between 1 V and 2 V of the output waveform.
 - F. t_t is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9677501QXA	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type
74ABTE16245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTE16245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTE16245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABTE16245WD	ACTIVE	CFP	WD	48	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity A0

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTE16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABTE16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTE16245DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ABTE16245DLR	SSOP	DL	48	1000	346.0	346.0	49.0

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

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